IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				rials and M	Ifg Informat	tion				
upplier Inform	ation														
Company name*			Company unique ID				Unique ID Authority				Respon	Response Date*			
onsemi											2024-05	2024-05-20			
Contact Name		Title - Contact				Phone - Contact*				Email -	Email - Contact*				
Product-Env-Stewa	rds	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
uthorized Represe	ntative*	Title - Representative				Phone - Representative*				Email -	Email - Representative*				
Product-Env-Stewa	rds	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Requeste	Requester Item Number Mfr Ite		em Number Mfr Item Name				Effective Date	Version	n]	Manufacturing Site		Weight*	UOM	Unit Type	
		S100	S100 1A 100V S		0V SCHOTTKY RECT		2024-05-20 PANJ		PANJITFG		67.9	mg	Each		
	Ploting / Grid Array Mo		Terminal Base A	Alloy	-STD-020 MS	I Pating	Dank Dead	pass Rody (Camparatu	May Time at Dog	k Tampara	tura Numb	ber of Reflow Cyo	plac	
8		CU Allov J-S1D-02		-31D-020 MS	SL Kaung	260	k Process Body Temperat		ure Max Time at Peak Tempera 30 seco			ber of Kellow Cy	nes		
omments	i (Sii) - aimealeu		O Anoy	J	L		200			30	seco	ius 3			
	ime at peak temperatu	ro during co	Idorina is 10-3	0 seconds											
	on regarding material		Ŭ												

RoHS Material Composition Declaration			Declaration Type *	Detailed						
RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information ir true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this fo										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.764	mg	Supplier	Silicon (Si)	7440-21-3		0.7585	mg
			В	Nickel (Ni)	7440-02-0		0.0011	mg
			Supplier	Gold (Au)	7440-57-5		0.0042	mg
			В	Arsenic (As)	7440-38-2		0.0002	mg
Die Attach Solder	2.25	mg	Supplier	Silver (Ag)	7440-22-4		0.0563	mg
			A	Lead (Pb)	7439-92-1	7a	2.0812	mg
			Supplier	Tin (Sn)	7440-31-5		0.1125	mg
Lead Frame	27.5903	mg	Supplier	Iron (Fe)	7439-89-6		0.0331	mg
			Supplier	Copper (Cu)	7440-50-8		27.5489	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0083	mg
Mold Compound-Black	36.69	mg		Metal Hydroxide	proprietary data		1.2842	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.9352	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1834	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		29.352	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.9352	mg
Plating	0.6057	mg	Supplier	Tin (Sn)	7440-31-5		0.6057	mg